

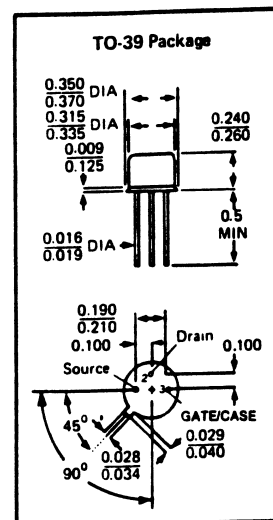
**HIGH VOLTAGE**  
**SILICON EPITAXIAL JUNCTION**  
**N-CHANNEL FIELD EFFECT TRANSISTORS**

**2N6449**  
**2N6450**

- HIGH  $V_{GSS}$  . . . 300V MIN (2N6449)
- HIGH POWER RATING . . . 5W

**ELECTRICAL DATA ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	2N6449	2N6450	UNITS
Drain to Gate Voltage	$BV_{DG0}$	300	200	Volts
Gate to Source Voltage	$BV_{GS0}$	-300	-200	Volts
Power Dissipation (25°C case)	$P_{DC}$	5		W
Derating Factor (Junction to Case)	$DFC$	3.33		$mW/^{\circ}C$
Power Dissipation (free air)	$P_{DA}$	800		mW
Derating Factor (free air)	$DFA$	5.33		$mW/^{\circ}C$
Junction Temp. (Oper. & Store)	$T_J$	-65 to 200		$^{\circ}C$
Lead Temp. (1/16" From Case 10 sec)	$T_L$	300		$^{\circ}C$
Continuous Forward Gate Current	$I_{GF}$	10		mA



**ELECTRICAL CHARACTERISTICS:  $T_A = 25^{\circ}C$  (UNLESS OTHERWISE STATED)**

PARAMETERS AND CONDITIONS	SYMBOL	2N6449			2N6450			UNITS
		Min.	Typ.	Max.	Min.	Typ.	Max.	
Gate Leakage Current $V_{GS} = -150V, V_{DS} = 0$	$I_{GSS}$		-1	-10				nA
Gate Leakage Current $V_{GS} = -150V, V_{DS} = 0, T_A = 150^{\circ}C$	$I_{GSS}$		-1	-10				$\mu A$
Gate Leakage Current $V_{GS} = -100V, V_{DS} = 0$	$I_{GSS}$		-1			-1	-10	nA
Gate Leakage Current $V_{GS} = -100V, V_{DS} = 0, T_A = 150^{\circ}C$	$I_{GSS}$		-1			-1	-10	$\mu A$
Gate Breakdown Voltage $I_G = -10\mu A, V_{DS} = 0$	$BV_{GSS}$	-300			-200			V
Pinch-Off Voltage $V_{DS} = 30V, I_D = 4nA$	$V_{PO}$	-2		-15			-15	V
Zero Bias Drain Current $V_{DS} = 30V, V_{GS} = 0$	$I_{DSS}^1$	2		10	2		10	mA
Forward Transfer Admittance $V_{DS} = 30V, V_{GS} = 0, f = 1 kHz$	$Y_{fs}^2$	500		3000	500		3000	$\mu mho$
Output Admittance $V_{DS} = 30V, V_{GS} = 0, f = 1 kHz$	$Y_{os}^2$			100			100	$\mu mho$
Input Capacitance $V_{DS} = 30V, V_{GS} = 0, f = 1 kHz$	$C_{iss}^2$			10			10	pf
Reverse Xfer Cap. $V_{DS} = 30V, V_{GS} = 0, f = 1 kHz$	$C_{rss}^2$			5			5	pf

- NOTES: 1. Measured using pulse techniques,  $t_w = 300\mu s$ , duty cycle < 2%.  
 2. Measured with bias conditions applied for less than 5 seconds.

